

innodisk

Innodisk Market Notes

November 2025

AGENDA

- [DRAM Market Trends](#)
- [DRAM Product Update](#)
- [NAND Flash Market Trends](#)
- [Flash Product Update](#)
- [EP Product Update](#)
- [Camera Product Update](#)

innodisk

DRAM Market & Product Update

Innodisk DRAM Business Unit

Tight DRAM Supply to Boost DDR5 Contract Prices—Profitability in 2026 Expected to Surpass HBM3e, Says TrendForce

29 October 2025

TrendForce's latest investigations show that server DRAM contract prices are strengthening in 4Q25, **driven by ongoing data center expansion among global CSPs**. This momentum is lifting overall DRAM pricing. Although final contract pricing for the quarter is still being negotiated, suppliers are showing a greater willingness **to raise quotes** as CSPs increase order volumes.

Looking ahead to 2026, global server shipments are expected to grow by around 4% annually. Meanwhile, CSPs are rapidly upgrading to HPC platforms to support massive AI models, driving up memory content per server. **This will push overall DRAM bit demand beyond prior expectations and extend the structural supply shortage.**

Thanks to server demand remaining strong, **DDR5 contract prices are expected to maintain an upward trajectory throughout 2026, especially in the first half of the year**. In contrast, given the increasingly competitive landscape among the three major suppliers for HBM3e—and the fact that buyers are holding healthy inventory levels—HBM contract prices are expected to shift into year-over-year decline.

TrendForce observes that as of 2Q25, HBM3e still commanded a price premium more than four times that of DDR5, providing much stronger profitability for suppliers. However, as DDR5 prices continue to rise, the gap between the two will narrow significantly in 2026.

Since HBM3e and DDR5 compete for the same production capacity, TrendForce expects that once this profitability shift occurs, suppliers may allocate more resources toward server DDR5 to secure earnings. Concurrently, with HBM3e pricing stabilizing and demand still solid, suppliers may also attempt to raise ASPs to maintain balanced profitability across their product portfolios.

Moving forward, the capacity allocation and pricing strategies between DDR5 and HBM among leading suppliers will become key variables shaping the next phase of the memory market.

(source: TrendForce)

DRAM Market Update

▪ Market and Supply Status

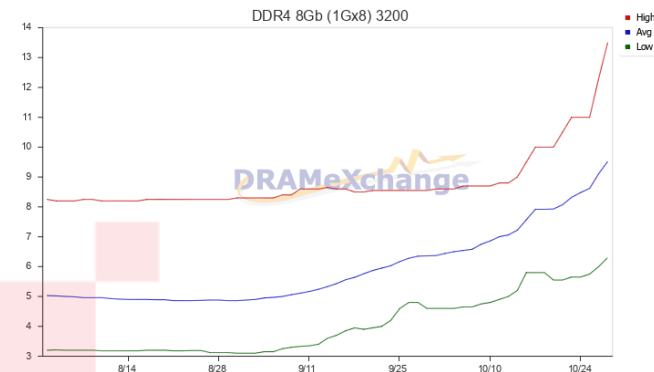
The supply of both DDR4 and DDR5 IC remains extremely tight. Samsung did not release official IC pricing and stop provide allocation in October, which directly led to a **panic buying** on spot market. As a result, the pace of price increases shows no signs of slowing down; spot prices for DDR5 have **even jumped by 100%**.

Beyond DRAM IC, Samsung also suspended the official pricing release for their PC DIMM and Server DIMM products for October.

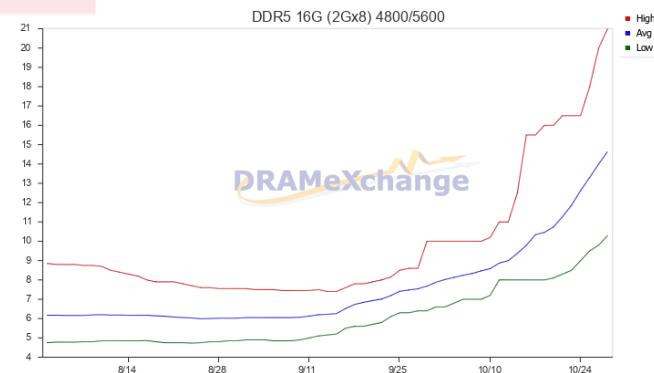
▪ Our Response and Advantages

Facing the DRAM IC manufacturers' supply crisis, our DDR4 4GB/8GB will focus on Nanya solution. Nanya supply is stable, crucially, this product line offers a product lifecycle that can be sustained **beyond 2027**. We urge you to adopt this long-term, stable supply product.

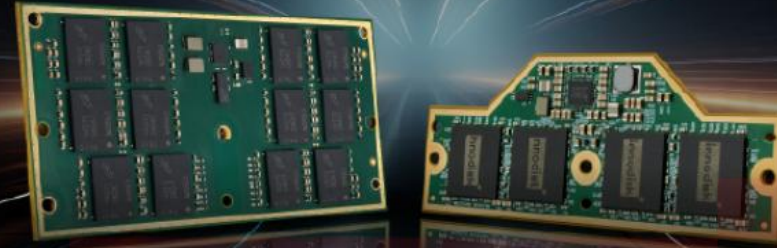
DDR4 8Gb IC spot price trend



DDR5 16Gb IC spot price trend



DRAM Module New Product

The Innodisk logo is a red rectangle with the word "innodisk" in white lowercase letters. Above the 'i' is a small blue square. The background of the entire slide features a dark blue grid with glowing blue lines radiating from the center, creating a sense of depth and technology.

CAMM2 / LPCAMM2

Double the Bandwidth, Half the Space

Innodisk's CAMM2 and LPCAMM2 redefine high-performance embedded memory with an ultra-slim form factor. The modules enhance signal integrity with simplified motherboard routing and reduce mounting space by up to 60%, allowing greater flexibility for custom cooling and system design.

Equipped with a 128-bit dual-channel architecture, CAMM2 delivers speeds up to 6400MT/s with DDR5, while LPCAMM2 reaches 8533MT/s with LPDDR5X at just 1.05V—cutting power consumption and extending system runtime. To support rugged deployments, the CAMM2 family features a screw-lock mounting that ensures strong vibration resistance. Meanwhile, LPCAMM2's modular LPDDR5X design further simplifies upgrades and replacements, making maintenance easier and more efficient.

These features make them ideal for rugged devices, CompactPCI systems, fanless solutions, and mini PCs.

NAND Flash Market & Product Update

NAND Flash Market Trends



NAND Flash Industry Outlook

Memory Supercycle Expectations Peak Amid Rising AI Demand

Morgan Stanley's recent report, "Memory Supercycle – Rising AI Tide Lifting All Boats," highlights that growing AI chip demand is driving the memory industry into a Supercycle potentially lasting until 2027.

A memory Supercycle is a prolonged boom marked by supply shortages, rising prices, and strong profit growth for manufacturers. Similar to the 2010s smartphone-driven surge benefiting Samsung, SK Hynix, and Micron, the current cycle is fueled by AI chip growth and high-performance computing's (HPC) demand for high bandwidth memory (HBM). Major players are ramping up HBM capacity, causing shortages in PC, mobile, and standard server DRAM and pushing prices higher.

NAND Flash is also seeing price gains due to increased enterprise SSD demand for AI servers and supply cuts from manufacturers.

This momentum suggests sustained growth and tight supply dynamics in the memory market over the next several years.



NAND Flash Industry Outlook

AI Storage demand drives HDD replacement, NAND Flash speeds Nearline SSD shift

TrendForce says booming AI inference demand for real-time, high-speed data access is driving HDD and SSD suppliers toward larger-capacity products. With HDDs in short supply, NAND Flash makers are rapidly developing 122TB–245TB Nearline SSDs to meet demand. High HAMR transition costs are limiting HDD capacity and pushing prices up from US\$0.012–0.013 to US\$0.015–0.016 per GB, weakening their cost edge.

NAND Flash, advancing through 3D stacking, scales faster. Over-200-layer designs raise density, and 2Tb QLC chips by 2026 will further lower Nearline SSD costs. AI inference needs rapid random reads and parameter access. SSDs deliver vastly higher IOPS, lower latency, and lower power per TB—helping data centers save energy and space, offsetting higher upfront costs.

TrendForce adds that even with HAMR cost gains ahead, NAND Flash keeps advantages in cost and scalability. For suppliers beyond phones and PCs, Nearline SSDs offer a vital chance to challenge HDDs and lead future data center storage.

PRODUCT HIGHLIGHTS



Innodisk Datacenter SSD

Reliability

Datacenters are running 24/7. High-reliability SSDs are essential to support the workload and data integrity.

Endurance

SSDs for datacenter should possess good endurance level for constant write and erase operations.

Performance

Datacenters process massive amount of data. High-performance and low latency is needed for the high data demand.

Security

SSDs with security features help to protect data against any unauthorized access or attack

Maintenance

Minimizing service down-time is critical. Reducing any debugging effort helps to improve datacenter operating efficiency.

Customization

Innodisk is able to customize the solution to meet the specific requirements of an application.

**Meeting the Key Aspects in
Modern Datacenters**



Product Highlight

Datacenter Boot SSD Selection



SATA 3TS9-P Series

Form Factors	2.5" SSD, M.2 2280		
Seq. Read/Write	550/520 MB/s (max.)		
Endurance (JEDEC 219, Enterprise workload, Warranty 5 Years)	Application	Recommended Capacity*	DWPD
	Mainstream	240GB-960GB	1
Operation Temp.	0°C - 70°C		



PCIe 4TS2-P Series

Form Factors	U.2, M.2 2280, M.2 22110, E1.S		
Seq. Read/Write	6950/4100 MB/s (max.)		
Endurance (JEDEC 219, Enterprise workload, Warranty 5 Years)	Application	Recommended Capacity*	DWPD
	Mainstream	240GB-960GB	1
Operation Temp.	0°C - 70°C		

*Higher capacity available. Please refer to product datasheet for more info.



Product Highlight

Data Center Storage SSD- PCIe Gen5



Features

- 3D eTLC/QLC
- NVMe 2.0
- Innodisk DSSD Feature Set
- Enhanced Thermal Management
- Customizable Features
- OCP 2.0

PCIe 5TS-P / 5QS-P Series

Form Factors	U.2, E1.S, E3.S, E3.L		
Seq. Read/Write	14 / 10 GB/s (max.)		
Endurance (JEDEC 219, Enterprise workload, Warranty 5 Years)	Application	Capacity*	DWPD
	Mainstream (eTLC)	1.9TB-15.3TB	1
	Mixed-use (eTLC)	1.6TB-12.8TB	3
	High-capacity (E3.L QLC)	128TB	TBA

innodisk

IPA/EP x OUTFRONT

Intelligent Peripheral Appliance, Embedded Peripheral Div.



innodisk

I/O SOLUTIONS BUILT FOR EXTREME CHALLENGES

Innodisk Industrial-Grade I/O Solutions

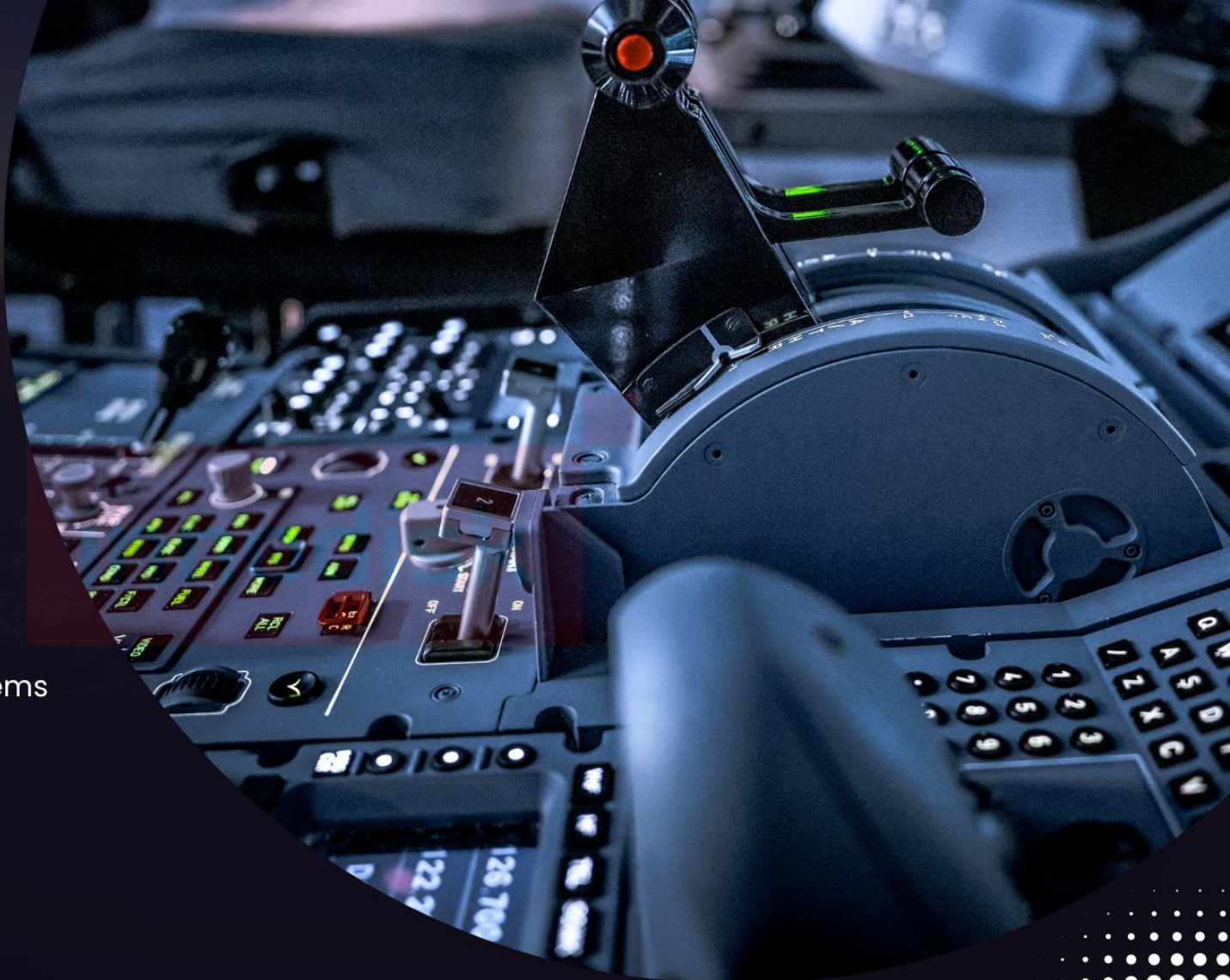


TABLE OF CONTENTS

1. Introduction
2. Challenges in Aerospace Systems
3. Innodisk I/O Module Highlights
4. Use Case Scenarios
5. Support & Procurement

Partner with EP: Faster, Smarter, and More Cost-Effective Solutions

- **Faster Time-to-Market**
- **One stop Solution**
- **High price performance ratio**
- **Reliable Quality You Can Trust**
- **Quick Technical Support**

Traditional I/O modules often face challenges in aircraft cabin environments....



High EMI and Unstable Communication

High EMI in dense cabin causes signal errors and unstable communication.



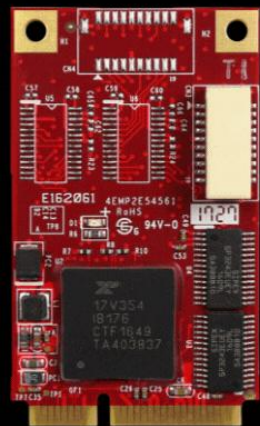
Limited Space and Challenging Cable Routing

Tight space in cockpit limits I/O card installation and cable routing.

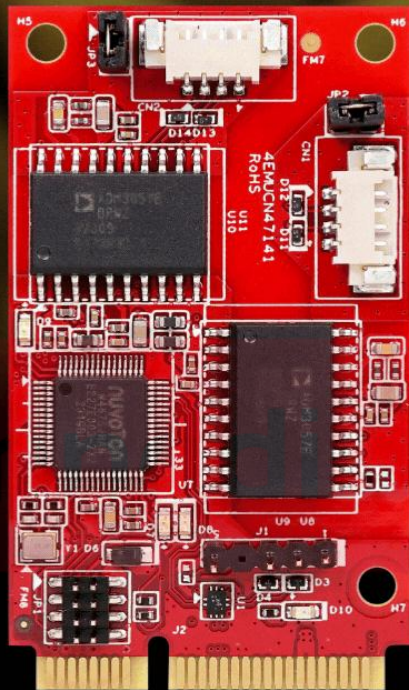


Durability and Thermal Stress Challenges

Avionic systems face thermal, vibration, and corrosion challenges during long-term operation.



Serial

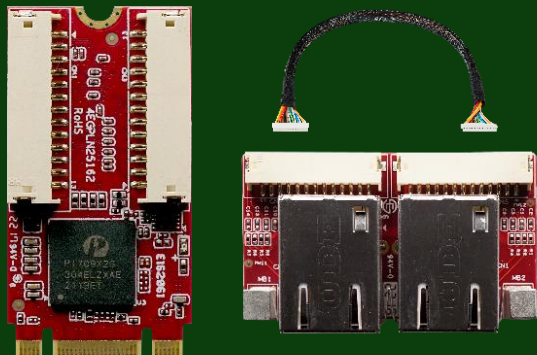


CAN Bus



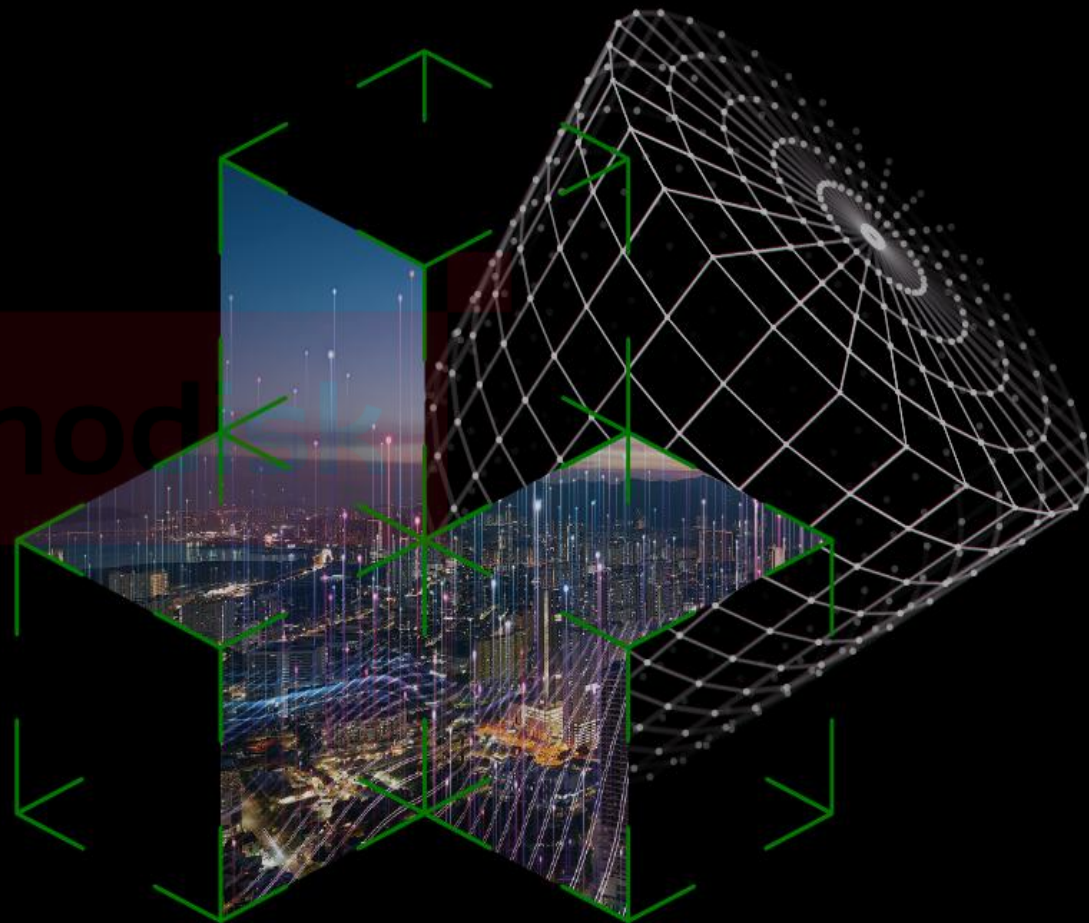
LAN

LAN"

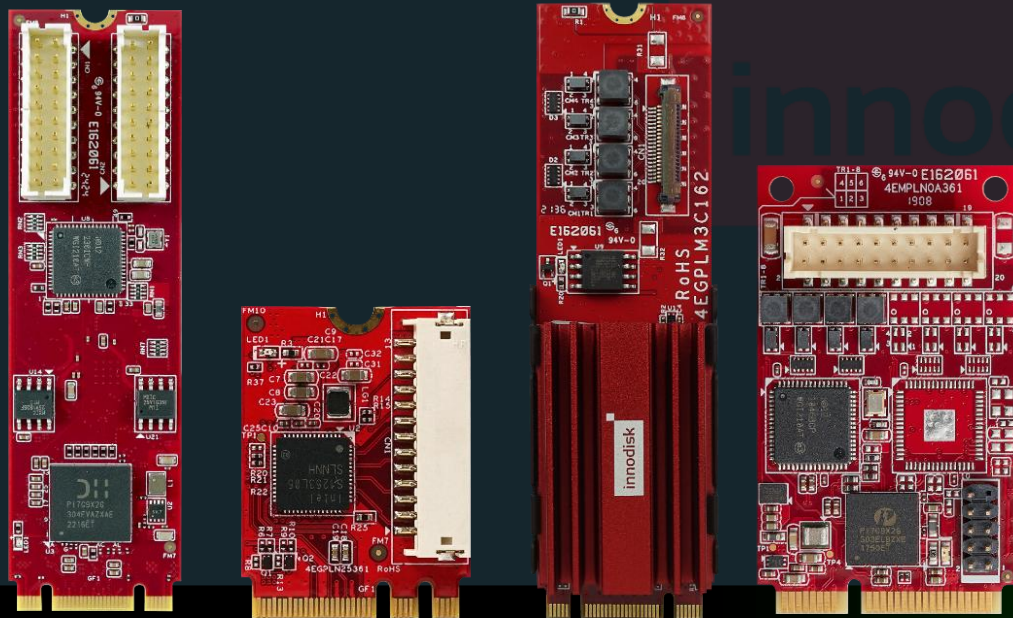


**RELIABLE AND
VERSATILE LAN SERIES**

innod



ADVANTAGES



1

Supports multi-speed networks (1GbE, 2.5GbE, 10GbE), ideal for different data throughput applications

2

Complies with ESD, EMC, and up to 2000V HiPOT/Surge protection

3

Compact design fits embedded devices with minimal interference

4

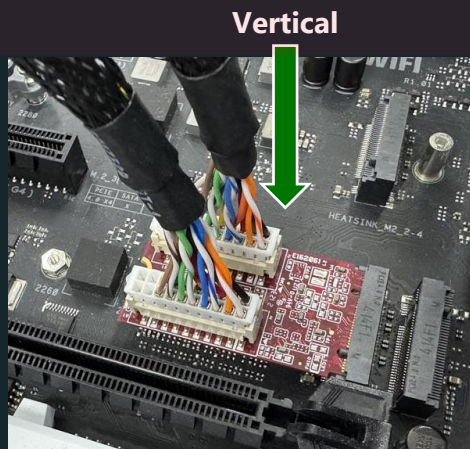
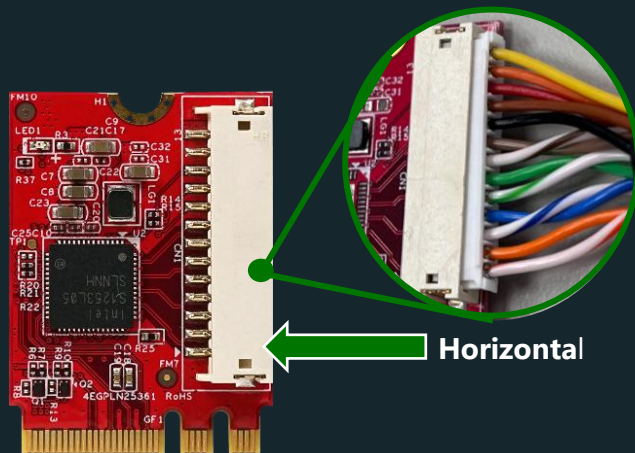
The on-board transformer design combines efficient signal stability and flexible cable design

5

Support wide temperature from -40 to 85 degrees suitable for harsh environments

HORIZONTAL DESIGN

Horizontal LAN cards feature ideal for **industrial automation** and **embedded applications** where **vertical clearance** is limited. In line with the trend of compact system design, horizontal connectors are designed to facilitate cable routing and minimize mechanical interference. From smart transportation to outdoor surveillance, horizontal designs excel with their **compact layout** and **stable performance** in constrained environments.



outdoor surveillance



industrial automation



Defense & Aerospace



Space limited products



EMPL-G202
mPCIe to 1/2 GbE
i210



EGPL-22S2
M.2 2242 to 1/2 ports
i226



EGPL-21S3
M.2 2242 to 1/2 ports
i226



EGPL-22S4
M.2 2242 to 1/2 ports
i226



EMPL-22S2
mPCIe to 1/2 ports
i226

Chip LAN

Redefining Flexibility in Connectivity

The Chip LAN architecture provides a rugged, modular alternative to fixed RJ45 connectors ideal for aerospace and defense. It enables mission-specific cabling and supports robust M12 X-Code connectors for IP67-level protection, ensuring reliable high-speed data transmission in harsh environments.



IP67 waterproof



Flexible Cable Design

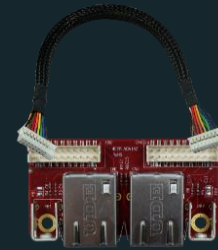


On-Board Transformer

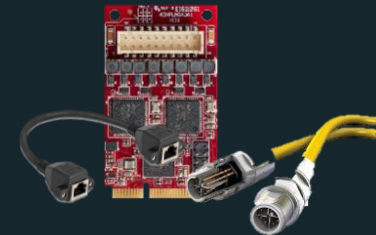


Wide Temp. Support

RJ45 VS Chip LAN



Fixed cable



Flexible cable

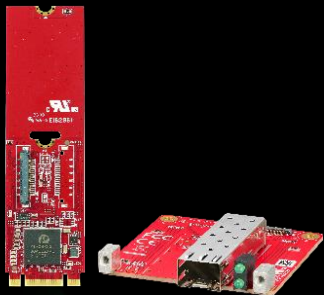


**M.2 Gbe SFP Network
Module**

innodisk



SFP Networking Solutions (M.2 2280/2242)



EGPL-G1F1



EGPL-G2F1

M.2 SFP Networking Solutions: Engineered for Smart Factories and Critical Networks

EGPL-G1F1 and EGPL-G2F1 are M.2 to SFP fiber network modules designed for industrial applications, offering single and dual GbE fiber connectivity respectively. With intel i210-IS controller and support multi-mode and single-mode fiber. Operating in wide temperature range of -40°C to 85°C, the modules meet industrial-grade shock and ESD standards, and support both windows and Linux systems. Ideal for smart manufacturing, remote surveillance, and medical communication scenarios requiring high-speed and stable connectivity.

<Applications>



Edge AI platform



Surveillance

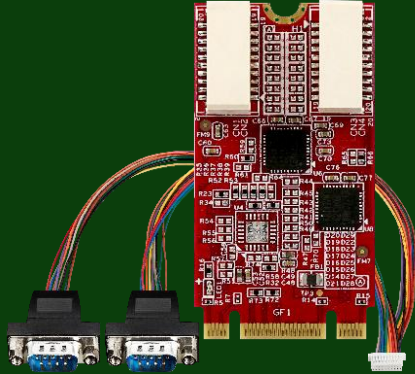


Drone



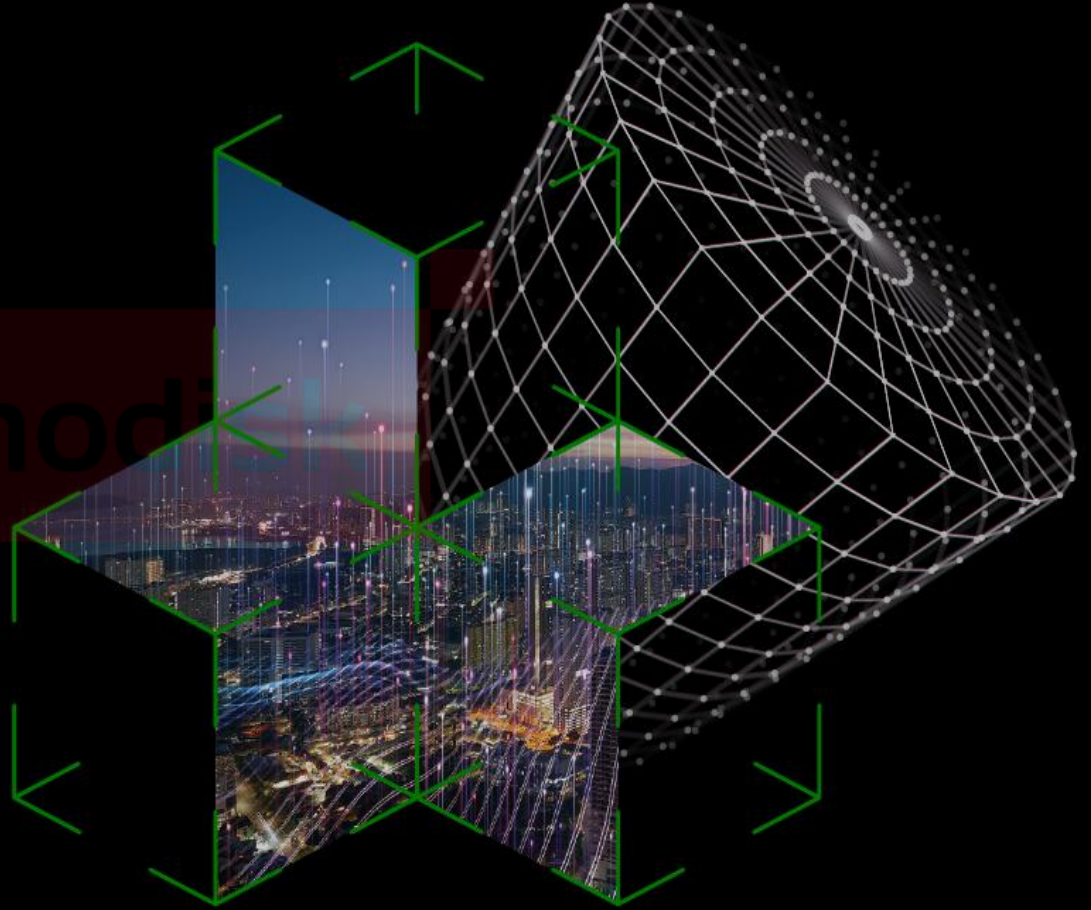
Industrial Automation

SERIAL™



**The Industrial Grade
Serial Solution You
Can Trust**

innod



ADVANTAGES



1

RS-232/422/485 mode configurable by software

2

2.5 kV HiPOT isolation, providing the reliable isolation protection in the market

3

Supports wide industrial temperature range (-40°C to 85°C) for harsh environments

4

Support different ports and form factors ensure high versatility for various applications

5

Offering exceptional ESD protection with 15kV air discharge and 8kV contact discharge



Industrial-Grade High-Stability Serial Solution

<Key Features>



HiPOT Protection

HiPOT (High Potential) protection is a high-voltage test that verifies the insulation strength of electrical components. By applying 2.5kV or more between power and ground or isolated circuits, it ensures there's no dangerous leakage current. This prevents electrical accident and equipment failures. Commonly used in industrial equipment, medical devices, power supplies, and communication systems, HiPOT protection safeguards safety and reliability in high-voltage environments.

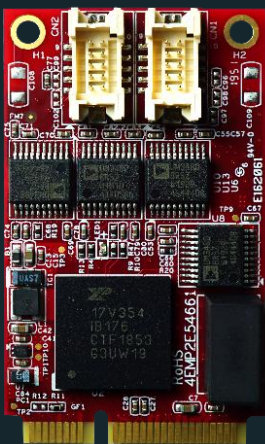


ESD
Contact-8kV
Air-15kV

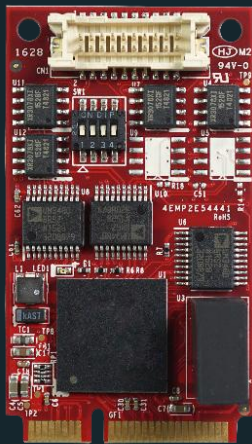


Wide Temperature
-40°~85°

<Applications>



EMP2-X2S1



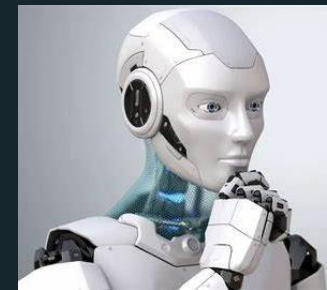
EMP2-X4S1



Automation



Transportation



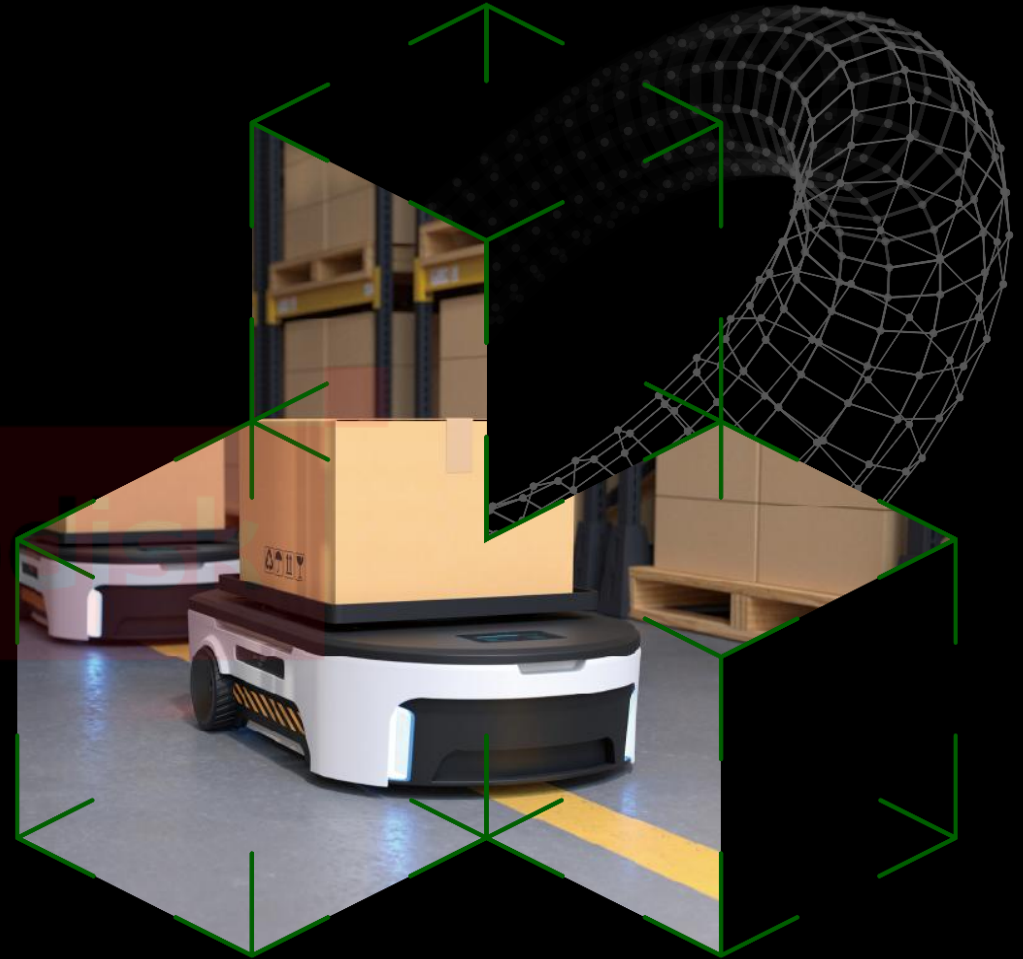
Humanoid Robot

CAN BUS™



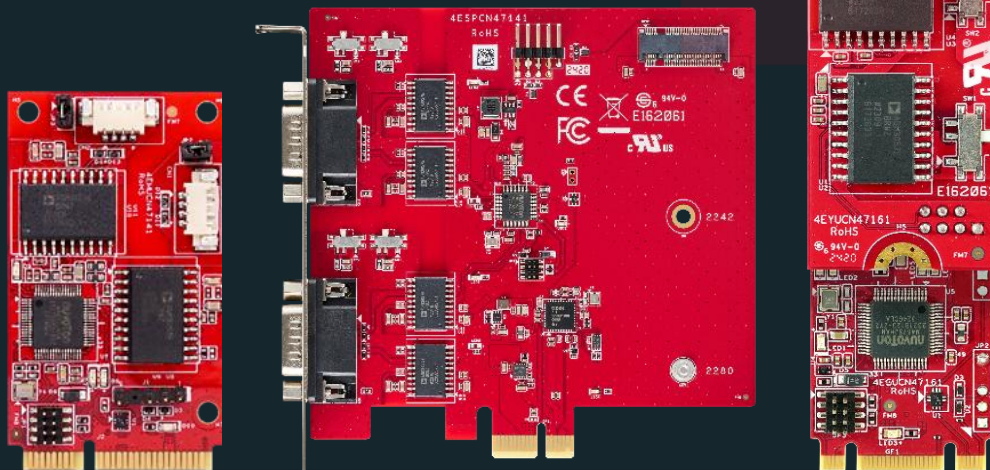
**The Industrial Grade
CAN Solution You Can
Trust**

inno



ADVANTAGES

innodisk



1

2.5 kV HiPOT isolation, providing the reliable isolation protection in the market

2

Hardware-software integration highly customizable for your data

3

Supports wide industrial temperature range (-40°C to 85°C) for harsh environments

4

Flexible connection options ensure high versatility for various applications

5

Offering exceptional ESD protection with 15kV air discharge and 8kV contact discharge

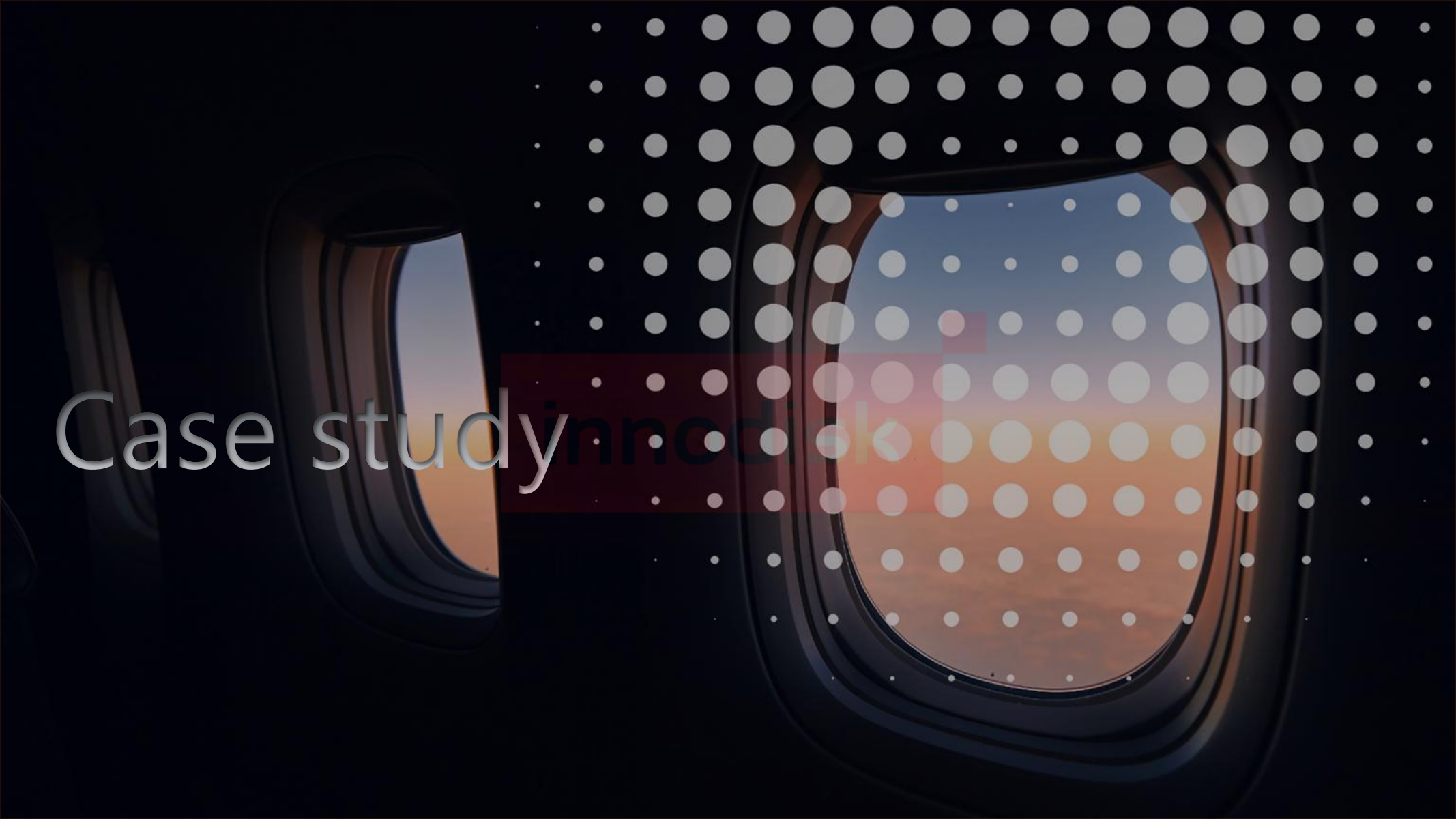
Multi- Platform Support

Flexible Integration Across Applications

© COPYRIGHT INNODISK CORPORATION P34



We offers extensive software platform support, covering major operating systems, communication protocols, programming languages, and development frameworks.

The background of the slide features a dark, atmospheric view from inside an airplane cabin, looking out through two oval windows. The windows show a soft, hazy sunset or sunrise with warm orange and blue tones. Overlaid on the entire image is a grid of semi-transparent white circles of varying sizes, creating a technical or digital aesthetic.

Case study

innodisk



Project : Cargo Drone



Item: EMUC-B202

USB to dual CAN us J1939 WT



Application:

- UAV Control Communication
- Ground Station Diagnostics

innodisk



Selling Point:

Innodisk's USB-to-CAN module enables reliable communication between the UAV's onboard control system and CAN-enabled devices, ensuring stable operation and real-time data exchange. It also supports ground station diagnostics, helping identify system issues and streamlining maintenance workflows.



Project : Avionics Bay



Product: EMPL-22S2

mPCIe to dual isolated 2.5GbE LAN horizontal module



Application:

- Multi-channel Network Integration for Avionics Systems

innodisk

Selling Point:



Modern avionics demand reliable connectivity in constrained environments with EMI interference, vibrations, and limited space. The EMPL-22S2 with Intel i210 delivers dual isolated slot, streamlining integration while reducing cabling complexity and board footprint.



Project : Military Defense



Product: EGPL-T102

M.2 2280 to Single 10GbE LAN Module



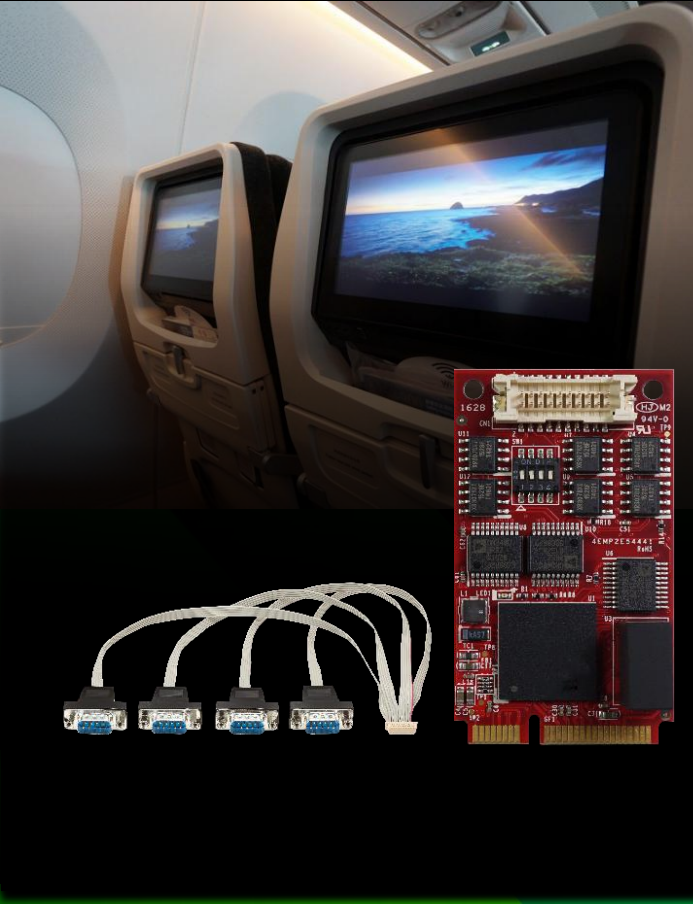
Application:

- Integration of VR LED Display
- Real-time Data Transmission
- Multi-VR Collaborative Work



Selling Point:

Military flight training requires high-speed, low-latency systems that can support multiple VR devices. Innodisk delivers reliable 10GbE solutions to meet the intense performance demands of modern air force simulations.



Project : Seat Power Box



Product: EMP2-X4S1

mPCIe to four Isolated RS-485 module



Application:

- Power Status Feedback
- Seat Power Group Control

innodisk

Selling Point:



Innodisk's EMP2-X4S1 provides stable RS-485 communication between the main controller and Seat Power Boxes, enabling real-time power control and usage feedback. Built for enclosed cabin environments, it offers 2.5 kV isolation, 15kV/8kV ESD protection, and wide temperature support (-40°C to 85°C), ensuring safe and reliable operation in harsh aerospace conditions.



Item	Form Factor	Photo	Model Name	Description	Isolation (2.5kV)	CAN FD	OutPut	CAN High Layer Protocol	Sample ready
1	M.2 2242		EGPC-B1S1	M.2 2242 to single isolated CAN Bus	✓		1	J1939 / CANopen	✓
2	M.2 2242		EGUC-F1S3	M.2 2242 to single isolated CAN Bus	✓	✓	1		upcoming
3	M.2 2260/2280		EGPC-B201	M.2 2260 or M.2 2280 to dual isolated CAN Bus 2.0B	✓		2	J1939 / CANopen	✓
4	M.2 2280		EGPC-B4S1	M.2 2280 to four isolated CAN Bus 2.0B	✓		4	J1939 / CANopen	✓
5	M.2 2280		EGPC-B2S1	M.2 2280 to dual isolated CAN Bus 2.0B	✓		2	J1939 / CANopen	✓
6	M.2 2280		EGUC-F2S3	M.2 2280 to dual isolated CAN FD	✓	✓	2		✓
7	M.2 2280		EGUC-F4S3	M.2 2280 to four Isolated CANFD	✓	✓	4		✓



CAN MODULE SELECTOR

Item	Form Factor	Photo	Model Name	Description	Isolation (2.5kV)	CAN FD	OutPut CAN	High Layer Protocol	Sample ready
1	mPCle		EMUC-B202	mPCle to dual Isolated CAN Bus	✓		2	J1939 / CANopen	✓
2	mPCle		EMUC-B2S3	USB to dual Isolated CAN Bus	✓		2	J1939 / CANopen	✓
3	mPCle		EMPC-B2S1	mPCle to dual isolated CAN Bus 2.0B	✓		2	J1939 / CANopen	✓
4	mPCle		EMUC-F2S3	mPCle to dual Isolated CANFD	✓	✓	2		✓



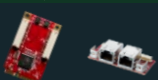
Item	Form Factor	Photo	Model Name	Description	Isolation (2.5kV)	CAN FD	OutPut CAN	High Layer Protocol	Sample ready
1	PCle		ESPC-F2S3	PCle to dual Isolated CANFD	✓	✓	2 /4/6		✓
2	PCle		ESPC-F4S3	PCle to four Isolated CANFD	✓	✓	4 / 6 /8		✓

innodisk

Item	Form Factor	Photo	Model Name	Controller	Port	Speed	Isolation	D. board	W.Temp	Sample ready
1	M.2 2230		EGPL-G104	I210	1	1 GbE	✓	✓	✓	✓
2	M.2 2230		EGPL-21S3	I226	1	2.5GbE	✓	✓	✓	✓
3	M.2 2242		EGPL-G102/ G202	I210	1 , 2	1 GbE	✓	✓	✓	✓
4	M.2 2242		EGPL-G105/ G205	I210	1 , 2	1 GbE	✓	✓	✓	✓
5	M.2 2242		EGPL-21S2/ 22S2	I226	1 , 2	2.5GbE	✓	✓	✓	✓
6	M.2 2242		EGPL-21S4/ 22S4	I226	1 , 2	2.5GbE	✓	✓	✓	✓
7	M.2 2280		EGPL-G101/ G201	I210	1 , 2	1 GbE	✓	✓	✓	✓
8	M.2 2280		EGPL-G1N3/ G2N3	I210	1 , 2	1 GbE	✓		✓	✓
9	M.2 2280		EGPL-21N1/ 22N1	I226	1 , 2	2.5GbE	✓		✓	✓
10	M.2 2280		EGPL-21S1/22S1	I226	1 , 2	2.5GbE	✓	✓	✓	✓
11	M.2 2280		EGPL-G401	i350	4	1 GbE	✓	✓		✓
12	M.2 2280		EGPL-T102	Marvell AQC113	1	10GbE		✓		✓

* W.Temp= Wide Temperatures D.board= Daughter board



Item	Form Factor	Photo	Model Name	Controller	Port	Speed	Isolation	D. board	W.Temp	Sample ready
1	mPCle		EMPL-G101/ G201	I210	1 , 2	1 GbE	✓	✓	✓	✓
2	mPCle		EMPL-G102/ G202	I210	1 , 2	1 GbE	✓	✓	✓	✓
3	mPCle		EMPL-G103/ G203	I210	1 , 2	1 GbE	✓		✓	✓
4	mPCle		EMPL-21N1/ 22N1	I226	1 , 2	2.5GbE	✓		✓	✓
5	mPCle		EMPL-21S1/ 22S1	I226	1 , 2	2.5GbE	✓	✓	✓	✓
6	mPCle		EMPL-21S2/ 22S2	I226	1 , 2	2.5GbE	✓	✓	✓	✓



Item	Form Factor	Photo	Model Name	Controller	Port	Speed	Isolation	D. board	W.Temp	Sample ready
1	PCIe		ELPL-G401	I210	4	1 GbE	✓		✓	✓
2	PCIe		ESPL-2401	I226	4	2.5GbE	✓		✓	✓

innodisk



Item	Form Factor	Photo	Model Name	Controller	Put	Speed	Isolation	D. board	W.Temp	Sample ready
1	M.2 2242		EGPL-G1F1	I210	1	GbE Fiber Optical		✓	✓	✓
2	M.2 2280		EGPL-G2F1	I210	2	GbE Fiber Optical		✓	✓	✓

innodisk



Item	Photo	Series	Form Factor	Output Port	RS-232	RS-422 RS-485	RS-232 RS-422 RS-485	Isolation (2.5Kv)
1		EGP2-X203/X403	M.2 2242	2/4	✓			
2		EGP2-X401	M.2 2242	2/4			✓	
3		EGP2-X4S1	M.2 2280	4		✓		✓
4		EMP2-X2S1	mPCIe	2	✓			✓
5		EMP2-X203/X403		2/4	✓			
6		EMP2-X202/X402		2/4		✓		
7		EMP2-X4S1/X4S2		4		✓		✓
8		EMP2-X404		4			✓	
9		EMP2-X801		8			✓	

innodisk

2025 September Product Release

SENSING INTELLIGENCE



EV2U-LOM1-RHCF

USB 2.0 2MP Fixed Focus
Camera Module



2M @ 30 FPS



HDR



Optional Housing

- 2.0 Interface, 2MP @ 30fps (Max. Resolution)
- Support HDR, ISP Inside
- Dynamic Range: 120dB
- Lens FOV (D / H / V) : 96° / 88° / 57°
- OS Support : Windows, Linux, Android, macOS (UVC)
- Compliant to USB 2.0 and USB Video Class
- Complies with CE / FCC Class A



HDR (High Dynamic Range)

HDR is a camera technology that captures a **broader range of brightness in challenging lighting**. By merging multiple shots with different exposures, HDR produces an image that accurately represents both bright and dark areas.

The dynamic range, measured in decibels (dB), shows the contrast between the brightest and darkest parts the sensor can capture, with **higher dB values indicating a wider range**. The human eye has a dynamic range of about 120 dB.

Short Exposure



Long Exposure



HDR Image



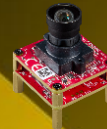
Scene: Outdoor Facial Recognition



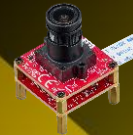
Scene: Indoor + Outdoor



EV2U-LOM1-RHCF
USB 2.0
2M@ 30 FPS
HDR/ 120dB



EV8M-OOM1-RHCF
MIPI CSI-2
8M@ 30 FPS
HDR/ 120 dB

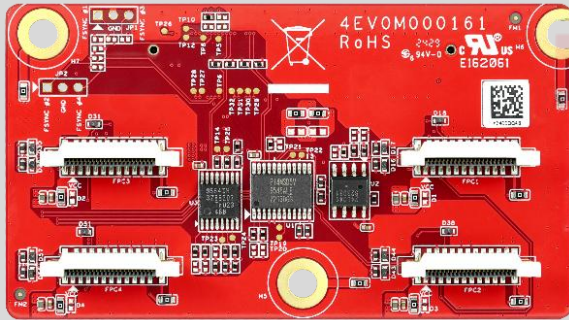


EVDm-OOM1-RHCF
MIPI CSI-2
13M@ 20 FPS
HDR/ 69dB



EB120-1S4M

SAMTEC 120-pin x1 to MIPI CSI-2 22-pin x4
Adapter Board



NVIDIA AGX Orin



MIPI CSI-2 Camera x4



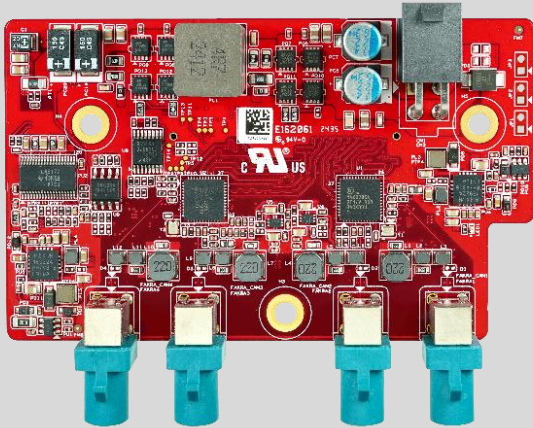
SAMTEC 120-pin

- Camera Interface : MIPI CSI-2 22-pin x4
- Host Interface : SAMTEC 120-pin x1



EB120-1S4F

SAMTEC 120-pin x1 to GMSL2 FAKRA Z x4
Adapter Board



NVIDIA AGX Orin



GMSL2 Camera x4



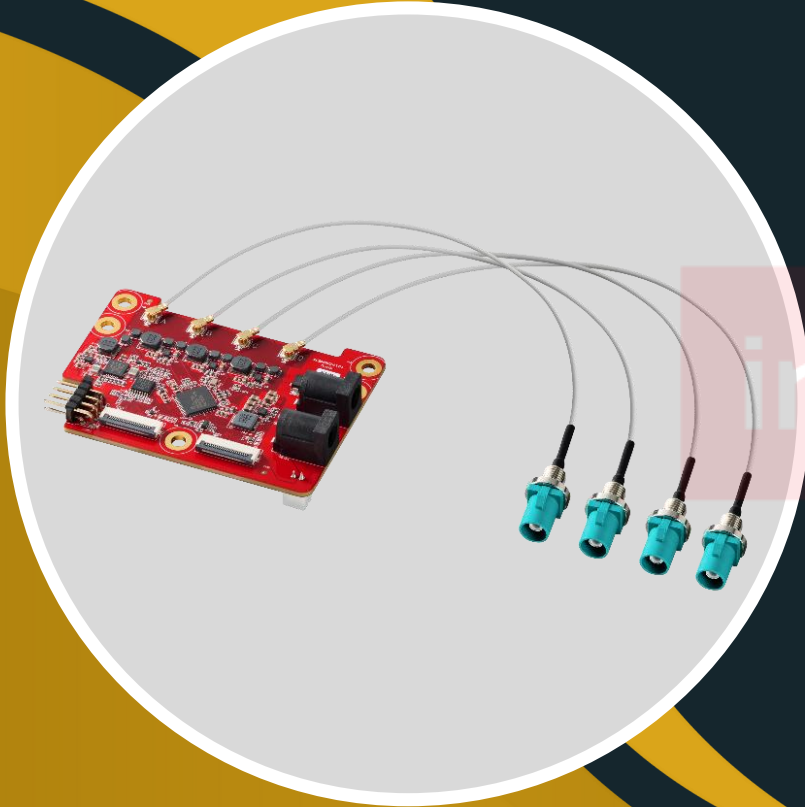
SAMTEC 120-pin

- Camera Interface: GMSL2™ FAKRA Z x4
- Host Interface: SAMTEC 120-pin x1
- Deserializer Chipset onboard: MAXIM MAX9296



EB022-2M4F

MIPI CSI-2 22-pin x2 to
GMSL2 IPEX FAKRA Z x4 Adapter Board



NVIDIA Jetson Orin



GMSL2 Camera x4

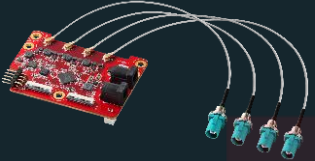


MIPI CSI-2 22-pin x2

- Camera Interface: GMSL2™ FAKRA Z x4
- Host Interface: MIPI CSI-2 22-pin x2
- Deserializer Chipset (Onboard): MAXIM MAX96724

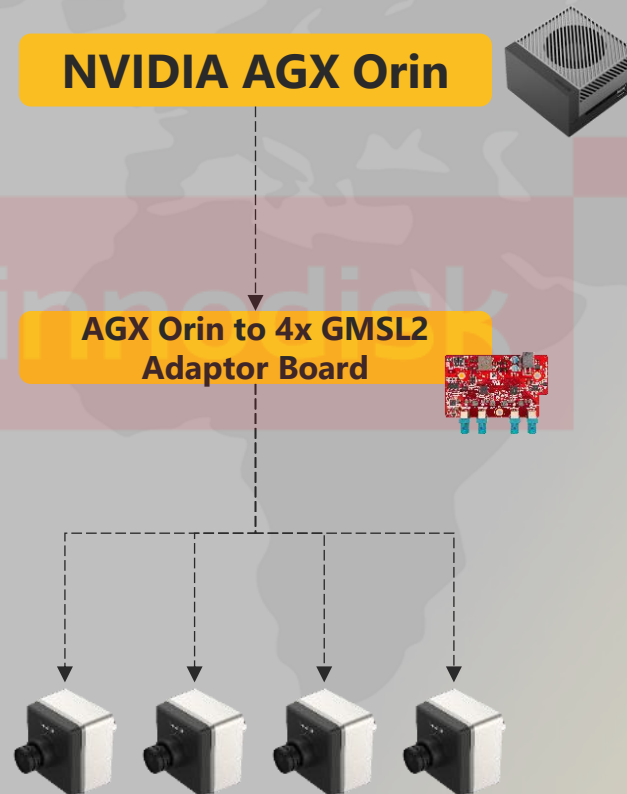


CAMERA ADAPTOR BOARD

Product Number	EB022-2M4F	EB120-1S4F	EB120-1S4M
Product Name	MIPI CSI-2 22-pins x2 to GMSL2 IPEX FAKRA Z x4 Adapter Board	SAMTEC 120-pins x1 to GMSL2 FAKRA Z x4 Adaptor Board	SAMTEC 120-pins x1 to MIPI CSI-2 22-pins x4 Adaptor Board
Product Image			
Deserializer	MAX96724	MAX9296A	NA
MIPI Camera Connectivity (Up to) 	NA	NA	✓ 4 x MIPI CSI-2 Camera
GMSL2 Camera Connectivity (Up to) 	✓ 8 x GMSL2 Camera (Orin Nano/NX) ✓ 16 x GMSL2 Camera (AGX Orin with EB120-1S4M)	✓ 4 x GMSL2 Camera	✓ 16 x GMSL2 Camera (AGX Orin with EB022-2M4F)
NVIDIA Platform Compatibility	➤ NVIDIA Jetson AGX Orin ➤ NVIDIA Jetson Orin Nano/ NX  	➤ NVIDIA Jetson AGX Orin 	➤ NVIDIA Jetson AGX Orin 



GMSL2 SUPPORT (MAX9296A with 4 Cameras)





GMSL2 SUPPORT (MAX96724 with 16 Cameras)



innodisk

ARCHITECT INTELLIGENCE